

<b>SPEC SHEET (FOR REFERENCE)</b>	SHEET No.	Rev.	Page.
	<b>G05034A</b>		1 of 1

TYPE : 6PT1603N3T\*\*

CHIP SIZE	0.36 * 0.36 mm
WAFER SIZE	6 inch
POSSIBLE DIE PER WAFER	119,000 pcs

Maximum Ratings(Ta=25°C)

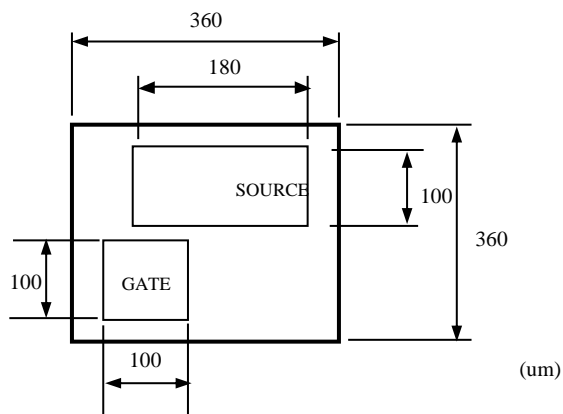
Characteristics	Symbol	Ratings	Unit
Drain-source voltage	VDSS	30	V
Gate-source voltage	VGSS	±20	V
Drain Current (DC)	ID	0.3	A

\* For Reference

WAFER PROBING SPEC (Ta=25°C)

No	MODE	LIMIT				CONDITIONS
		MIN.	Typ	MAX.	UNIT	
1	IGSS			±5	uA	VGS=±20V VDS=0V
2	IDSS			1	uA	VDS=30V
3	BVDSS	32			V	ID=100uA
4	VTH	1		2.4	V	ID=250uA
5	RDS(on)		1.7	2.5	Ω	VGS=4V ID=100mA
6	Yfs	100			mS	VDS=10V Id=100mA

※ Built-in ZD between Gate and Source.



NOTE: